**MEETING AGENDA**

**Organization: TIA TR42 Thermal Performance of 1-Pair Cables Task Group**

**Chair: Todd Harpel – todd.harpel@leviton.com**

**Date: Friday, October 16th, 2020**

**Time: 10 a.m. - 11 a.m. EDT**

**Meeting Minutes**

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TIA is actively seeking participation in TR-42.7 standards projects from the user and general interest communities.

Agenda

Administrative

Call to order

Attendance

Members of the task group marked as present participated in the meeting.

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| --- | --- | --- | --- |
| P |  Member | Company |  |
| P | Bob Voss | Panduit | Bob.Voss@panduit.com |
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Agenda review and approval

TR42\_7 Thermal Performance of 1-Pair Cabling Agenda- Meeting 4 – Approved

Previous meeting report review and approval

* TIA Thermal Performance of 1-Pair task group Meeting Report - Meeting 3

Distribution of documents and contributions

* Agenda for meeting 4
* TIA Thermal Performance of 1-Pair task group Meeting Report - Meeting 3
* STL Single Pair Ethernet PoE Thermal Performance.pdf – Sterlite Technologies

Discussion and review of contributions

STL Single Pair Ethernet PoE Thermal Performance.pdf – Sterlite Technologies

Darshana reviewed the Sterlite contribution showing measured temperature rise for a 23 AWG S/FTP (solid conductor) single-pair cable in bundle sizes of 37 and 61 cables at currents of 0.5A and 2.0A.

Darshana showed a table with different bundle sizes and additional current values that she indicated would be filled in going forward with measured data.

It was requested that the steps between 0.5A and 2.0A be in increments of 0.5A

There was discussion on whether an 18AWG cable should be stranded or solid.

Wayne Hopkinson did not think that the temperature rise would be significantly different as long as the cable constructions were similar.

Bob Voss mentioned that he may have some data on a solid conductor 18AWG bundle to present in the future that could be compared to previous data on a stranded cable bundle with 18AWG conductors.

Sterling mentioned that it might be useful to measure the surface temperature of the bundle during the testing. This could lead to a way of correlating the bundle surface temp to the temperature of a cable at the center of the bundle. Additionally it would be useful to insert temp probes at each layer of a bundle to create a temp profile across the bundle.

Old Business/Action Items

## Chris D. and Bob V. to apply data from CommScope model to previously submitted measured data. – No report for this meeting.

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Next meetings

* Friday October 30th, 10:00 a.m. – 11:00 a.m. EDT

Adjournment

The meeting was conducted in accordance with TIA Engineering Manual and concluded at 10:45.